


Serial No.: 09/944,015

REMARKS

No new matter has been added. The Applicants again request entry of the amendments as set forth in the Appendices hereto prior to examination of the application on the merits.

Respectfully submitted,



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Enclosures: Version of Specification with Markings to Show Changes Made
 Version of Claims with Markings to Show Changes Made



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VERSION OF SPECIFICATION WITH MARKINGS TO SHOW CHANGES MADE

Please replace Paragraph [0001] as follows:

[0001] This application is a continuation of application Serial No. 09/429,392, filed October 28, 1999, [pending]now United States Patent 6,316,824 B1, issued November 13, 2001, which is a divisional of application Serial No. 09/193,469, filed November 17, 1998, now United States Patent 6,091,136, issued July 18, 2000, which is a divisional of application Serial No. 08/878,935, filed June 19, 1997, now United States Patent 5,879,965, issued March 9, 1999.

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Serial No.: 09/944,015

VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

1. (Amended) An electronic device comprising:
 - an integrated circuit semiconductor die having at least one bond pad thereon;
 - a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame formed by one of compression molding and injection molding;
 - an adhesive attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
 - at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to [said]at least one lead finger of [the]said plurality of lead fingers of said conductive plastic lead frame; and
 - encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of at least one lead of said conductive plastic lead frame.
2. (Amended) An electronic device comprising:
 - an integrated circuit semiconductor die having at least one bond pad thereon;
 - a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame formed by one of stamping and etching;
 - an adhesive for attaching a portion of said integrated circuit semiconductor die to a portion of said conductive lead frame;
 - at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of the plurality of lead fingers of said conductive plastic lead frame; and
 - encapsulating material for encapsulating a portion of said integrated circuit semiconductor die and for encapsulating a portion of said at least one lead finger of said conductive plastic lead frame.

3. (Amended) An electronic device comprising:
an integrated circuit semiconductor die having at least one bond pad thereon;
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of [the]said plurality of lead fingers;
an adhesive for attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to [said]at least one lead finger of said conductive plastic lead frame;
and
encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of said at least one lead of said conductive plastic lead frame.

5. (Amended) The circuit card of claim 4, wherein said plastic lead frame comprises a plastic lead frame structure coated with [an]said intrinsic conductive polymer.

10. (Amended) The computer system of claim 9, wherein said plastic lead frame comprises a plastic lead frame structure coated with [an]said intrinsic conductive polymeric material.